

Features

- Surface Mount Package Ideally Suited for Automated Insertion
- Very Low Leakage Current
- **Lead Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 3 and 4)**

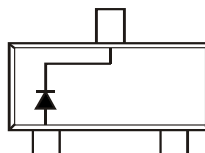
Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagram
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.008 grams (approximate)

SOT-23



TOP VIEW


 TOP VIEW
 Internal Schematic

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	85	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	60	V
Forward Continuous Current (Note 1)	I _{FM}	215	mA
Repetitive Peak Forward Current	I _{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	4.0	A
		1.0	
		0.5	

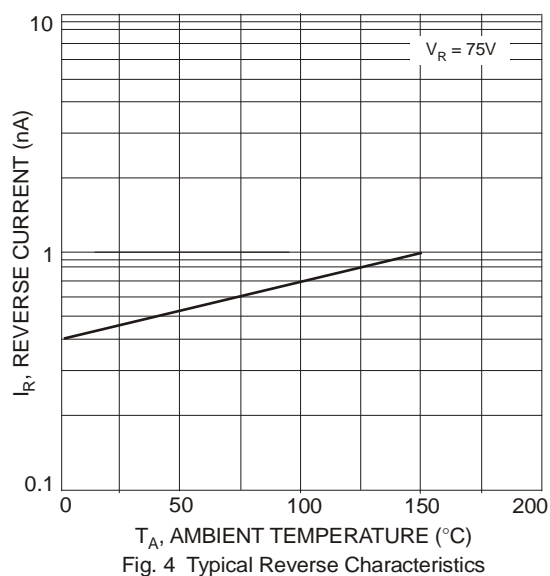
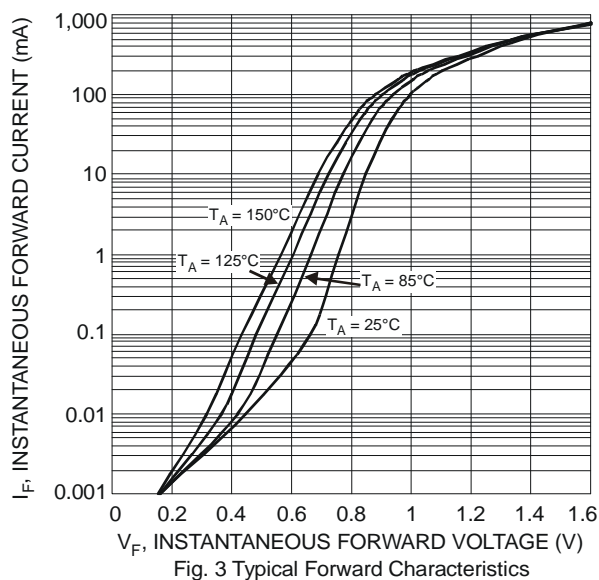
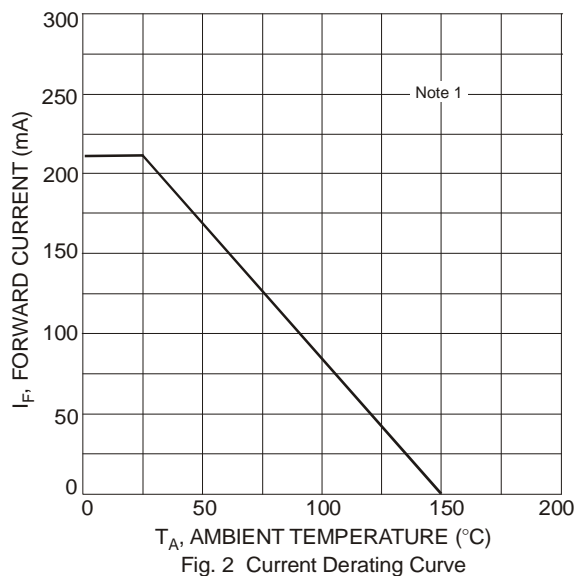
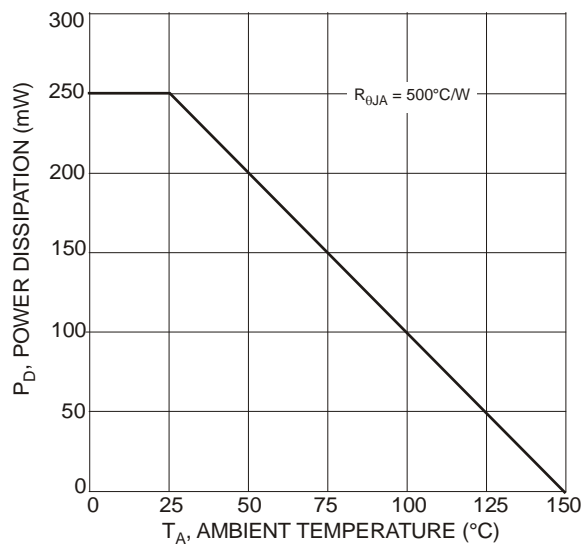
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1) @T _A = 25°C	P _D	250	mW
Thermal Resistance Junction to Ambient Air (Note 1) @T _A = 25°C	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	V _{(BR)R}	85	—	—	V	I _R = 100μA
Forward Voltage	V _F	—	—	0.90	V	I _F = 1.0mA
				1.0		I _F = 10mA
				1.1		I _F = 50mA
				1.25		I _F = 150mA
Leakage Current (Note 2)	I _R	—	—	5.0	nA	V _R = 75V
				80	nA	V _R = 75V, T _j = 150°C
Total Capacitance	C _T	—	2	—	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	—	3.0	μs	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

- Notes:
1. Part mounted on FR-4 PC board with pad layout as shown on page 3.
 2. Short duration pulse test used to minimize self-heating effect.
 3. No purposefully added lead. Halogen and Antimony Free.
 4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

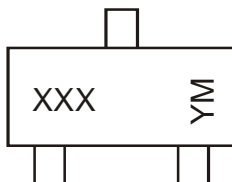


Ordering Information (Note 5)

Part Number	Case	Packaging
BAS116-7-F	SOT-23	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



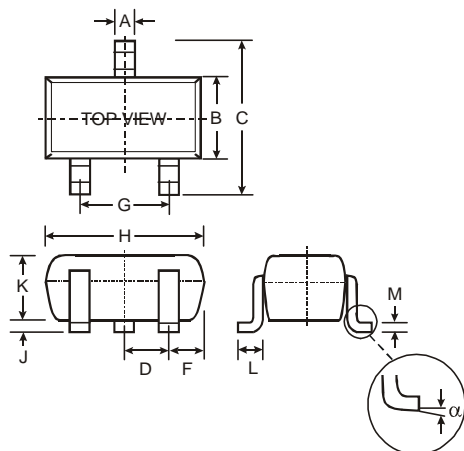
XXX = Product Type Marking Code; K50, K54
 YM = Date Code Marking
 Y = Year ex: N = 2002
 M = Month ex: 9 = September

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	M	N	P	R	S	T	U	V	W	X	Y	Z

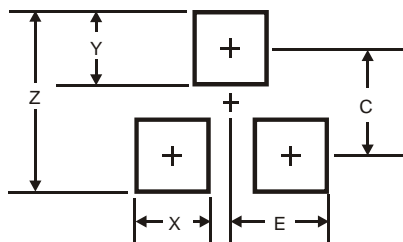
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-23		
Dim	Min	Max
A	0.37	0.51
B	1.20	1.40
C	2.30	2.50
D	0.89	1.03
F	0.45	0.60
G	1.78	2.05
H	2.80	3.00
J	0.013	0.10
K	0.903	1.10
L	0.45	0.61
M	0.085	0.180
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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